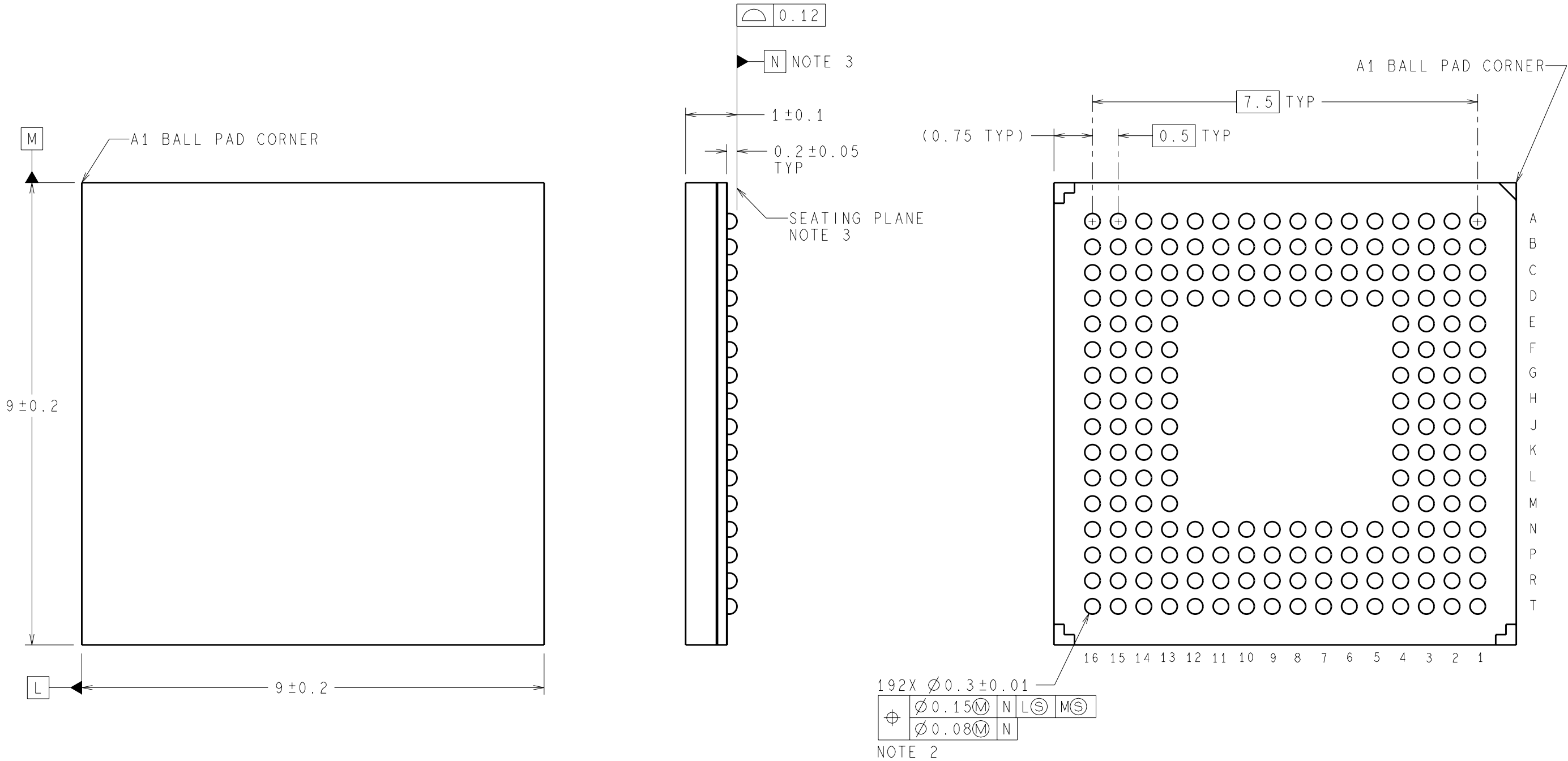


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	905	12/03/2002	TL/AP



NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
- DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- NO JEDEC REGISTRATION AS OF DECEMBER 2002.

DIMENSIONS ARE IN MILLIMETERS

APPROVALS		DATE	National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	T. LEQUANG	12/03/2002		
DFTG. CHK.	MARTA SUCHY	12/03/2002	FBGA, PLASTIC, LAMINATED, 9 X 9 X 1mm BODY, 192 BALL, 0.5mm PITCH	
ENGR. CHK.	ASHOK PRABHU	12/03/2002		
PROJECTION		SCALE	SIZE	DRAWING NUMBER
MM		NTS	B	(SC)MKT-SLH192A
FORMERLY: N/A		SHEET 1 of 1		